



Click [here](#) for the 3D model.

General Information

Series	SMD Indust COG HT200C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Low Loss
Features	High Temp, Ultra-Stable, Low Loss
RoHS	Yes
Termination	Gold
Marking	No
AEC-Q200	No
Typical Component Weight	40 mg
Miscellaneous	Moisture Sensitive Packaging. Gold (Au) 1.97 - 11.8 micro inches.
Shelf Life	26 Weeks
MSL	1

Dimensions

Chip Size	1210
L	3.2mm +/-0.2mm
W	2.5mm +/-0.2mm
T	1.25mm +/-0.15mm
S	1.5mm MIN
B	0.5mm +/-0.25mm

Packaging Specifications

Packaging	Waffle, Tray
Packaging Quantity	80

Specifications

Capacitance	0.1 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+200°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.